ON TAT INDUSTRIAL COMPANY

SPECIFICATION

Product Model: YX350HV15-CT (Rev.B)

Designed by	R&D Checked by	Quality Department by	Approved by

Approval by Customer

OK NG, Problem survey: Approved By _____

Revision Record

A2014-06-26NEW ISSUEB2014-10-21Chang CTP ICII <th>REV NO.</th> <th>REV DATE</th> <th>CONTENTS</th> <th>Note</th>	REV NO.	REV DATE	CONTENTS	Note
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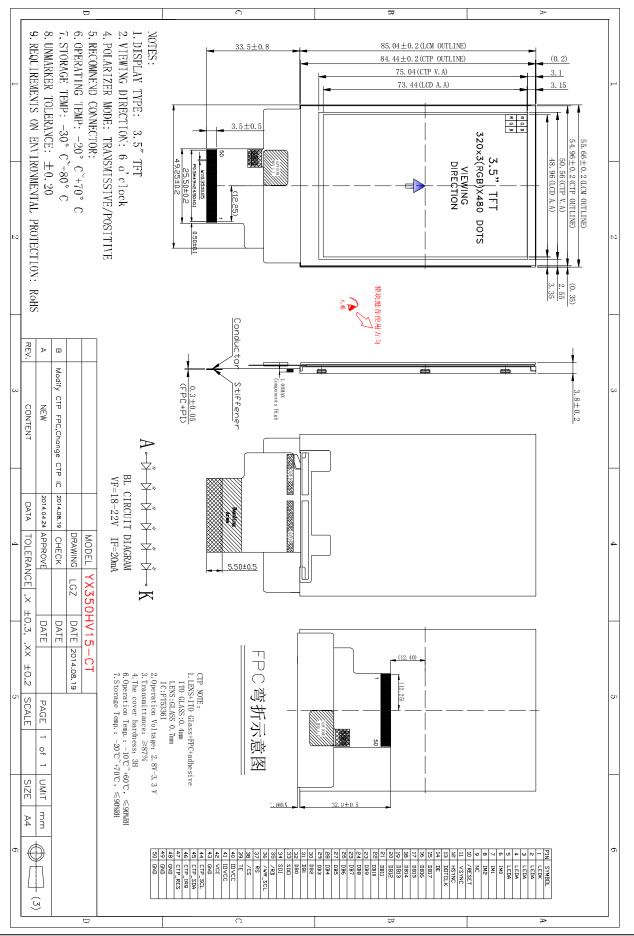
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1. Numbering System

2. TFT General Information

ITEM	STANDARD VALUES	UNITS
LCD type	3.5"TFT With CTP	
Dot arrangement	320(RGB)×480	dots
Color filter array	RGB vertical stripe	
Display mode	TN / Transmission / Normally White	
Viewing Direction	6 o'clock	
TFT Driver IC	HX8357D	
CTP type	G+G	
Surface Treatment	3Н	
CTP Driver IC	FT5336I	
Module size	55.66(W)×85.04(H)×3.8(T)	mm
TFT Active area	48.96(W)×73.44(H)	mm
CTP Active area	48.96(W)×73.44(H)	mm
Dot pitch	0.153(W)×0.153(H)	mm
Interface	4-lines_8bit / 3-lines_9bit SPI 8-/ 9-/16-/18-bit 8080-series system interface 16-/18-bit RGB interface	
Operating temperature	-20 ~ +70	Ĉ
Storage temperature	-30 ~ +80	ĉ
Back Light	6 White LED in serial	
Weight	TBD	g

3. External Dimensions



4. Interface Description

Pin	Symbol	Description.					
1	LEDK	LED backlight (Cathode).					
2	LEDA	LED backlight (Anode).					
3	LEDA	LED backlight (Anode).					
4	LEDA	LED backlight (Anode).					
5	LEDA	LED backlight (Anode).					
		System interface Mode					
6	IMO	IM2 IM1 IM0 Interface mode DB Pin					
		0 0 0 i80-system 18-bit interface DB[17:0]					
7	IM1	0 0 1 i80-system 9-bit interface DB[8:0]					
		010i80-system 16-bit interfaceDB[15:0]011i80-system 8-bit interfaceDB[7:0]					
		0 1 1 i80-system 8-bit interface DB[7:0] 1 0 1 3-wires_9-bit SPI /CS,SDI,SDO,SCL					
8	IM2	1 0 1 3-wires_9-bit SP1 7CS,SDI,SDO,SCL 1 1 1 4-wires 8-bit SP1 /CS,RS,SDI,SDO,SCL					
9	NC	NC					
10	/RESET	Reset input pin, Active "L".					
11	VSYNC	Vertical sync signal in RGB I/F.					
12	HSYNC	Horizontal sync signal in RGB I/F.					
13	DOTCLK	Pixel clock signal in RGB I/F.					
14	DE	Data enable signal in RGB I/F mode					
15	DB17						
16	DB16						
17	DB15						
18	DB14						
19	DB13						
20	DB12	18-bit parallel bi-directional data bus for MPU system:					
21	DB11	8-bit I/F: DB[7:0] is used.					
22	DB10	9-bit I/F: DB[8:0] is used. 16-bit I/F: DB[15:0] is used.					
23	DB9	24-bit I/F: DB[17:0] is used.					
24	DB8	10 hit input data hua far DOD 1/5					
25	DB7	18-bit input data bus for RGB I/F. 16-bit/pixel: DB[17:13]=R[4:0], DB[11:6]=G[5:0] and DB[5:1]=B[4:0];					
26	DB6	18-bit/pixel: DB[17:12]=R[5:0], DB[11:6]=G[5:0] and DB[5:0]=B[5:0];					
27	DB5	Connect unused pins to GND.					
28	DB4						
29	DB3						
30	DB2						
31	DB1						
32	DB0						
	<u></u>						

33	SDO	Serial output signal in SPI I/F.
34	SDI	Serial input signal in SPI I/F.
35	/RD	Reads strobe signal to write data when /RD is "Low" in MPU interface.
36	/WR_SCL	MCU: Serves as a write signal and writes data at the rising edge. SPI: SCL pin as Serial Clock when operates in the serial interface.
37	RS	Display data / command selection in 80-series MPU I/F. RS = "0" : Command RS = "1" : Display data.
38	/CS	Chip select input pin ("Low" enable) in MPU I/F and SPI I/F.
39	TE	Tearing effect output pin to synchronize MPU to frame writing.
40	IOVCC	I/O power supply.
41	IOVCC	I/O power supply.
42	VCI	System power supply.
43	GND	Power ground
44	CTP_SCL	I2C clock line
45	CTP_SDA	I2C data line
46	CTP_IRQ	Interrupt
47	CTP_RES	CTP reset line
48	GND	Power ground
49	GND	Power ground
50	GND	Power ground

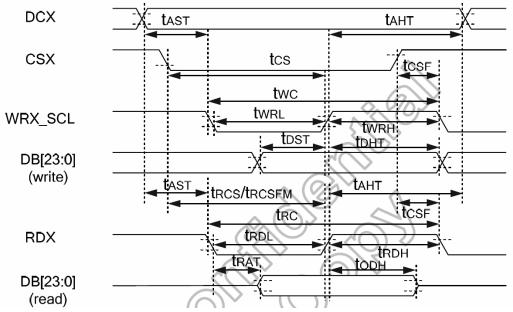
5. Absolute Maximum Ratings

Item	Symbol	Min.	Max.	Unit
Logic Supply Voltage	IOVCC	-0.3	4.6	V
Analog Supply Voltage	VCC	-0.3	4.6	V
Input Voltage	Vin	-0.3	IOVCC+0.5	V
Operating Temperature	Тор	-20	70	°C
Storage Temperature	Тѕт	-30	80	°C
Storage Humidity	HD	20	90	%RH

6. DC Characteristics

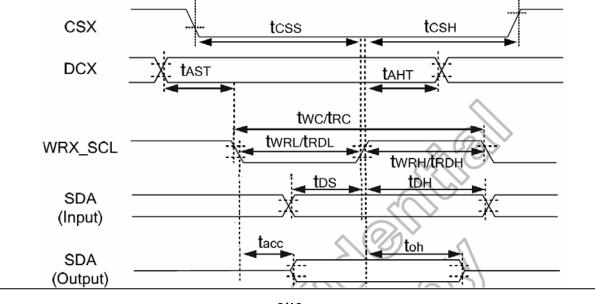
ltem	Symbol	Min.	Тур.	Max.	Unit	Remark
Logic Supply Voltage	IOVCC	1.65	1.8/2.8	3.3	V	-
Analog Supply Voltage	VCC	2.5	2.8	3.3	V	-
Input High Voltage	V _{IH}	0.7IOVCC	-	IOVCC	V	Digital input pins
Input Low Voltage	V _{IL}	GND	I	0.3IOVCC	V	Digital input pins
Output High Voltage	V _{OH}	0.8IOVCC	-	IOVCC	V	Digital output pins
Output Low Voltage	V _{OL}	GND	-	0.2IOVCC	V	Digital output pins
I/O Leak Current	ILI	-1.0	-	1.0	uA	-

7. Timing Characteristics7.1 i80-System Interface Timing Characteristics



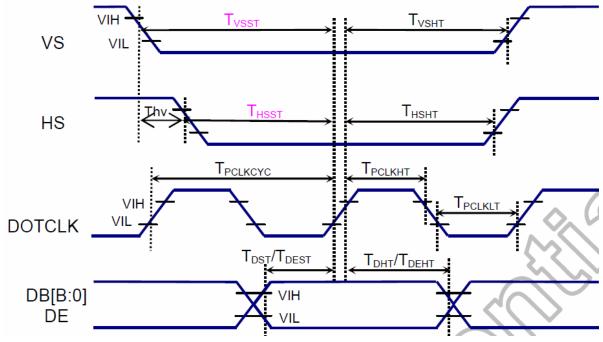
Signal	Symbol	Parameter	Min.	Max.	Unit	Description	
DCX	t ast	Address setup time	0	-	ns		
DCA	t AHT	Address hold time (Write/Read)	10	-	115	-	
	tcs 🦱	Chip select setup time (Write)	10	-			
CSX	trcs	Chip select setup time (Read register)	45	-	ns		
037	t RCSFM	Chip select setup time (GRAM)	355	-	115	-	
0	tcsF	Chip select wait time (Write/Read)	10	-			
	twc	Write cycle (write register)	50	-			
	twc	Write cycle (write GRAM@SLPOUT)	47	-			
WRX_SCL	twc	Write cycle (write GRAM@SLPIN)	100	-	ns	-	
	[™] twRH	Control pulse "H" duration	15	-			
\sim	twrl	Control pulse "L" duration 15 -					
	trc	Read cycle (read register)	160	-			
	trc	Read cycle (GRAM)	450	-			
RDX	t rdh	Control pulse "H" duration	90	-	ns	-	
	t RDL	Control pulse "L" duration(read register)	35	-			
	trdl	Control pulse "L" duration(GRAM)	345	-			
	tdst.	Data setup time	10	-			
	t DHT	Data hold time	10	-		For maximum CL=30pF	
DB[23:0]	t rat	Read access time(read register)	-	40	ns	For minimum CL=30pF	
	t rat	Read access time(GRAM)	-	340		For minimum CL=opF	
	t odh	Output disable time	20	80			

7.2 Display Serial Interface Timing Characteristics (SPI system)

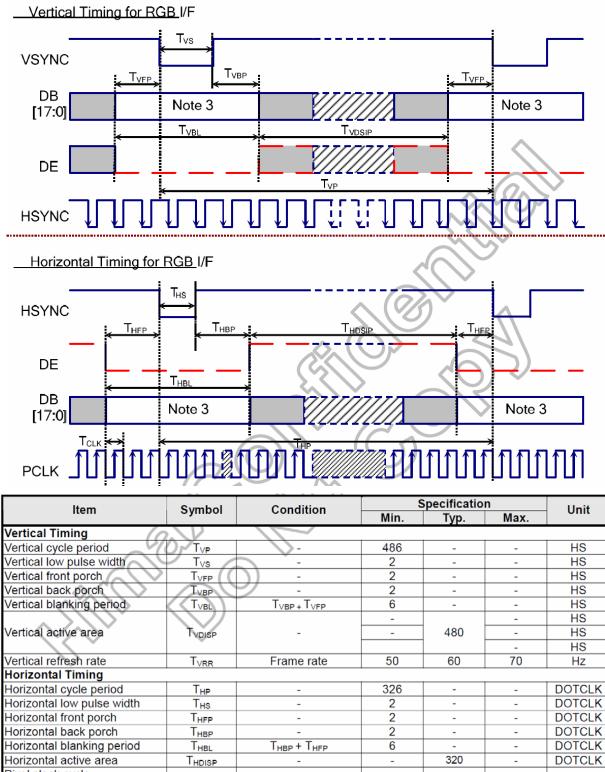


Signal	Symbol	Parameter	Min.	Max.	Unit	Description
	tcss Chip select setup time (15	-		
csx	tcss	Chip select setup time (Read)	60	-	ns	
COA	tcsн	Chip select hold time (Write)	15	-	113	-
	tcsн	Chip select hold time (Read)	65	-		
DCX	t AST	Address setup time	0	-	ns	
DCA	tант	Address hold time (Write/Read)	10	-	115	-
WRX_SCL	twc	Write cycle	66	-		
(Write)	twĸн	Control pulse "H" duration	15	-	ns	-
(write)	twrL	Control pulse "L" duration	15	-		
WRX SCL	trc	Read cycle	150	-		
(Read)	t RDH	Control pulse "H" duration	60	-	ns	-
(Read)	t RDL	Control pulse "L" duration	60	-		
SDA 🔿	tos	Data setup time	10	-	200	
(Input)	toн	Data hold time	10	-	ns	For maximum CL=30pF
SDA	tacc	Read access time	10	50	ns	For minimum C∟=8pF
(Output)	toн	Output disable time	15	50	115	

7.3 RGB Interface Timing Characteristics

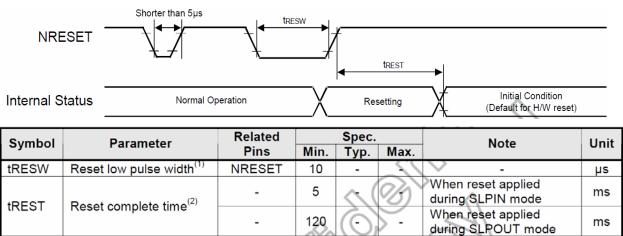


ltem	Symbol	Condition			Unit	
item	Symbol	Symbol Condition		Тур.	Max.	
Pixel low pulse width	T _{CLKLT}	$(S) \bigvee$	15 🦯 (シャ	-	ns
Pixel high pulse width	T _{CLKHT}	V/A	15	2-	-	ns
Vertical Sync. set-up time	T _{VSST}		15	>-	-	ns
Vertical Sync. hold time	T _{VSHT}		15	-	-	ns
Horizontal Sync. set-up time	T _{HSST}	\bigcirc \land \land	15	-	-	ns
Horizontal Sync. hold time	T _{HSHT>} (15	-	-	ns
Data Enable set-up time	TDEST		15	-	-	ns
Data Enable hold time	TDEHT		15	-	-	ns
Data set-up time	T _{DST}		15	-	-	ns
Data hold time	T _{DHT}	$\land (O)$	15	-	-	ns
Phase difference of sync signal falling edge	Thv <	25	0	-	320	Dotclk



Horizontal Timing									
T _{HP}	-	326	-	-	DOTCL				
T _{HS}	-	2	-	-	DOTCL				
THEP	-	2	-	-	DOTCL				
T _{HBP}	-	2	-	-	DOTCL				
T _{HBL}	T _{HBP} + T _{HFP}	6	-	-	DOTCL				
THDISP	-	-	320	-	DOTCL				
fclkcyc	-	9	-	-	MHz				
	THS THEP THBP THBL THDISP	THS - ТHFP - THBP - THBL THBP + THFP THDISP -	THS - 2 THFP - 2 THBP - 2 THBL THBP + THFP 6 THDISP - -	THS - 2 - THFP - 2 - THFP - 2 - THFP - 2 - THBP - 2 - THBL THBP + THFP 6 - THDISP - - 320	T _{HS} - 2 - - T _{HFP} - 2 - - T _{HBP} - 2 - - T _{HBL} T _{HBP} + T _{HFP} 6 - - T _{HDISP} - - 320 -				

7.4 Reset Timing Characteristics



8. Backlight Charasterics

A⊶ → ⊸ K

ltem	Symbol	MIN	TYP	MAX	UNIT	Test Condition
Supply Voltage	Vf	18.0	19.8	21.0	V	lf=20mA
Supply Current	lf	-	20	30	mA	-
Luminous Intensity for LCM	-	300	350	-	Cd/m ²	lf=20mA
Uniformity for LCM	-	80	-	-	%	lf=20mA
Life Time	-	20000	-	-	Hr	lf=20mA
Backlight Color				White		

9.	Optical	Characteristics
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Item		Symbol	Condition	Min.	Тур.	Max.	Unit	Note
Transmittance (without Polarizer)		T (%)	_	_	(14.74)	_	_	
Contrast Ratio		CR	⊖=0	400	500	—	—	(1)(2)
	Rising	T _R	Normal viewing	_	(4)	(8)	msec	(1)(3)
Response time	Falling	T _F	angle —	_	(12)	(24)		
Color gamut		S(%)			(60)		%	
	White	W _x		(0.283)	(0.303)	(0.323)		(1)(4)
		Wy		(0.305)	(0.325)	(0.345)		
	Red	Rx		(0.606)	(0.626)	(0.646)		
Color		Ry		(0.314)	(0.334)	(0.354)		
chromaticity (CIE1931)	Green	Gx		(0.257)	(0.277)	(0.297)		CF glass
		Gy		(0.529)	(0.549)	(0.569)		Ū
	Blue	Вx		(0.122)	(0.142)	(0.162)		
	Diue	Ву		(0.102)	(0.122)	(0.142)		
	Hor.	θL		60	70	_		Viewing
Viewing angle		θR		60	70			Angle base on using EWV
	le Ver.	θu	CR>10	60	70	_		
		Θρ		40	60	_		Polarizer, Reference Only
Optima View Direction			(5)					

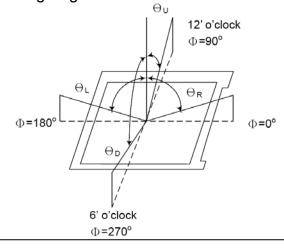
Measuring Condition:

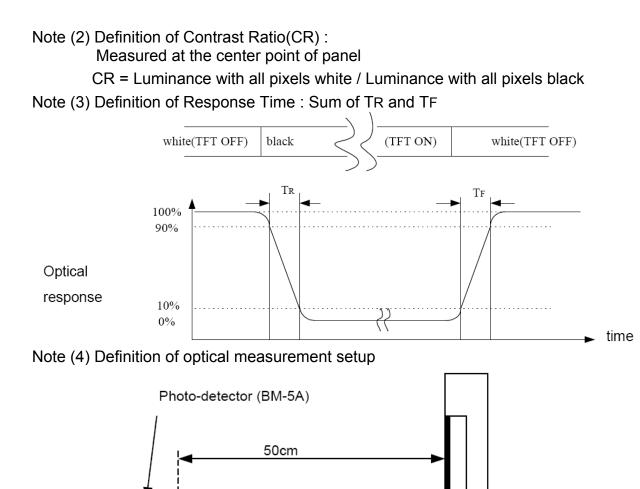
Dark room, 25±2°C, 15min. warm-up time.

Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

Note (1) Definition of Viewing Angle :





LCD panel

Field=1°

Center of panel

10. Reliability Test Conditions And Methods

NO.	TEST ITEMS	TEST CONDITION	INSPECTION AFTER TEST				
1	High Temperature Storage	80℃±2℃×200Hours					
2	Low Temperature Storage	-30℃±2℃×200Hours					
3	High Temperature Operating	70℃±2℃×120Hours	Inspection after 2~4hours				
4	Low Temperature Operating	-20℃±2℃×120Hours	storage at room temperature,the samples should be free from				
5	Temperature Cycle(Storage)	-20℃ ← 25℃ ← 70℃ (30min) (5min) (30min) 1cycle Total 10cycle	defects: 1,Air bublle in the LCD. 2,Sealleak. 3,Non-display. 4,Missing segments.				
6	Damp Proof Test (Storage)	50℃±5℃×90%RH×120Hours	5,Glass crack. 6,Current IDD is twice higher than initial value.				
7	Vibration Test	Frequency:10Hz~55Hz~10Hz Amplitude:1.5M X,Y,Z direction for total 3hours (Packing Condition)	7,The surface shall be free from damage. 8,The electric charateristic requirements shall be				
8	Drooping Test	Drop to the ground from 1M height one time every side of carton. (Packing Condition)	satisfied.				
9	ESD Test	Voltage:±8KV,R:330Ω,C:150PF,Air Mode,10times					

REMARK:

1, The Test samples should be applied to only one test item.

2,Sample side for each test item is 5~10pcs.

3,For Damp Proof Test,Pure water(Resistance $> 10M\Omega$)should be used.

4, In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judge as a good part.

5,EL evaluation should be excepted from reliability test with humidity and temperature:Some defects such as black spot/blemish can happen by natural chemical reaction with humidity and Fluorescence EL has.

6, Failure Judgment Criterion: Basic Specification Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.

11. Inspection Standard

This standard apply to C-STN/TFT module

1. Spot check plan:

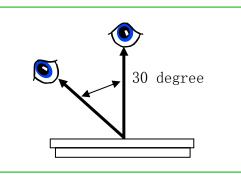
According to spot check level II, MIL-STD-105D Level II, the rank of accept or reject is below:

3A 级、2A 级: major non-conformance: AQL 0.25 minor non-conformance: AQL

0.4

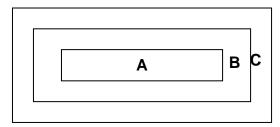
A级:major non-conformance: AQL 0.65 minor non-conformance: AQL 1.

2. Inspection condition:



Under daylight lamp 20 $\sim40W_{\textrm{P}}$ product distance inspector'eye 30cm,incline degree 30°.

3. LCD area define:



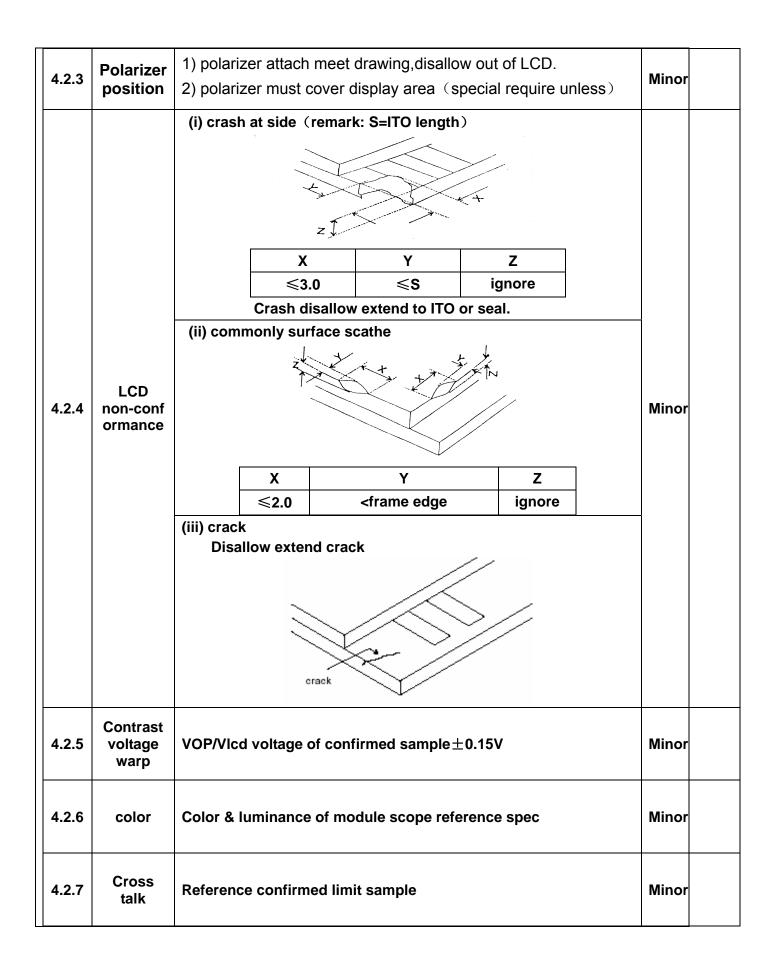
Area A: display area

Area B: VA area

Area C: out of VA area, not in sight after assemby

Remark :non-conformance at area C,but is OK that isn't influence raliability of product & assembly by customer.

NO.	Item		Inspection				n standard			
4.1.1	Function non-conf mance	2) Mis	short ction o	ction or function abnormaly						
4.1.2	miss	No ma	No matter miss what component						_ major	
4.1.3	Out of size	ze Module	e dime	nsion c	out of spec				1	
4.2 A	ppearan	ce non-con	forma	ance						
NO.	ltem			Insp	ection sta	nda	rd		Rate	
		dot non-cont $\Phi = \frac{(x+y)}{2}$			neΦ			У		
		A grade	e Most approve q'ty							
	Black or white spot	size (mm)	ł	Α	В		С			
4.2.1		Ф≤0.10	Ф≤0.10		ignore			Minor		
-	(power on)	0.10<Φ≤	10<Ф≤0.15		3					
	•,	0.15<Φ≤	15<Ф≤0.20		2		ignor	e		
		0.20<Ф≤	20<Φ≤0.25		1					
	M	0.25<0	0.25<Ф		0					
		Most approv	st approve 4 damages, dot to dot ≥10mm							
		A grade							_	
	Black or white line (power on)	Size	Size(mm)		Most approve			q'ty	_	
4.2.2 white line (power		L(length)	W(w	idth)	Α		В	С		
		ignore	W≤	0.03	ignore					
		L≤5.0	0.03< W≤0.05		2				Minor	
		L≤3.0		5< 0.07	1			ignore		
			0.07	′ <w< td=""><td colspan="2">Treat with dot non-conformance</td><td></td><td></td></w<>	Treat with dot non-conformance					
		Most approv	- 2 dar	magaa	line te line	<u>></u> 1	0.000		- 1	



12. Handling Precautions

12.1 Mounting method

The LCD panel of SC LCD module consists of two thin glass plates with polarizes which easily be damaged. And since the module in so constructed as to be fixed by utilizing fitting holes in the printed circuit board.

Extreme care should be needed when handling the LCD modules.

12.2 Caution of LCD handling and cleaning

When cleaning the display surface, Use soft cloth with solvent

[recommended below] and wipe lightly

- Isopropyl alcohol
- Ethyl alcohol

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

Water

Aromatics

Do not wipe ITO pad area with the dry or hard materials that will damage the ITO patterns Do not use the following solvent on the pad or prevent it from being contaminated:

- Soldering flux
- Chlorine (Cl), Salfur (S)

If goods were sent without being sili8con coated on the pad, ITO patterns could be damaged due to the corrosion as time goes on.

If ITO corrosion happen by miss-handling or using some materials such as Chlorine (CI), Salfur (S) from customer, Responsibility is on customer.

12.3 Caution against static charge

The LCD module use C-MOS LSI drivers, so we recommended that you:

Connect any unused input terminal to Vdd or Vss, do not input any signals before power is turned on, and ground your body, work/assembly areas, assembly equipment to protect against static electricity.

12.4 packing

- Module employ LCD elements and must be treated as such.
- Avoid intense shock and falls from a height.
- To prevent modules from degradation, do not operate or store them exposed direct to sunshine or high temperature/humidity

12.5 Caution for operation

- It is an indispensable condition to drive LCD's within the specified voltage limit since the higher voltage then the limit cause the shorter LCD life.
- An electrochemical reaction due to direct current causes LCD's undesirable deterioration, so that the use of direct current drive should be avoided.
- Response time will be extremely delayed at lower temperature then the operating temperature range and on the other hand at higher temperature LCD's how dark color in them. However those phenomena do not mean malfunction or out of order with LCD's, which will come back in the specified operation temperature.
- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the maximum operating temperature, 50%Rh or less is required.

12.6 storage

In the case of storing for a long period of time for instance, for years for the purpose or replacement use, the following ways are recommended.

- Storage in a polyethylene bag with the opening sealed so as not to enter fresh air outside in it . And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light's keeping the storage temperature range.
- Storing with no touch on polarizer surface by the anything else.
 [It is recommended to store them as they have been contained in the inner container at the time of delivery from us

12.7 Safety

- It is recommendable to crash damaged or unnecessary LCD's into pieces and wash off liquid crystal by either of solvents such as acetone and ethanol, which should be burned up later.
- When any liquid leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water

13. Precaution For Use

13.1

A limit sample should be provided by the both parties on an occasion when the both parties agreed its necessity. Judgment by a limit sample shall take effect after the limit sample has been established and confirmed by the both parties.

13.2

On the following occasions, the handing of problem should be decided through discussion and agreement between responsible of the both parties.

- When a question is arisen in this specification
- When a new problem is arisen which is not specified in this specifications
- When an inspection specifications change or operating condition change in customer is reported to GT LCD , and some problem is arisen in this specification due to the change
- When a new problem is arisen at the customer's operating set for sample evaluation in the customer site.

14. Packing Method

